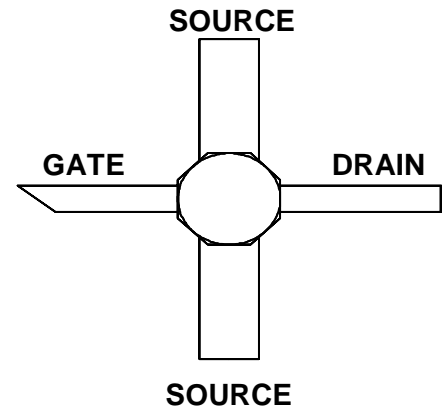


FEATURES

- +20 dBm Typical Power at 18 GHz
- 7.5 dB Typical Power Gain at 18 GHz
- 16 dB Typical SSG at 2 GHz
- 0.8 dB Typical Noise Figure at 2 GHz
- Low Intermodulation Distortion
- Color-coded by I_{DSS} range


DESCRIPTION AND APPLICATIONS

The LP7612P70 is a packaged Aluminum Gallium Arsenide / Indium Gallium Arsenide (AlGaAs/InGaAs) Pseudomorphic High Electron Mobility Transistor (PHEMT), utilizing an Electron-Beam direct-write 0.25 μm by 200 μm Schottky barrier gate. The recessed "mushroom" Ti/Pt/Au gate structure minimizes parasitic gate-source and gate resistances. The epitaxial structure and processing have been optimized for high dynamic range. The LP7612's active areas are passivated with Si_3N_4 , and the P70-52 ceramic package is ideal for low-cost, high-performance applications that require a surface-mount package. Packages are color-coded by I_{DSS} range.

Typical applications include high dynamic range receiver preamplifiers for commercial applications including Cellular/PCS systems, broad bandwidth commercial instrumentation and military EW amplifiers, and commercial Space applications.

The LP7612 may be procured in a variety of grades, depending upon specific user requirements. Standard lot screening is patterned after MIL-STD-19500, JANC grade.

PERFORMANCE SPECIFICATIONS ($T_A = 25^\circ\text{C}$)

SYMBOLS	PARAMETERS	MIN	TYP	MAX	UNITS
I_{DSS}	Saturated Drain-Source Current $V_{DS} = 2\text{V}$ $V_{GS} = 0\text{V}$	40	50	65	mA
P_{1dB}	Output Power at 1dB Gain Compression at $f = 18\text{ GHz}$ $V_{DS} = 5.0\text{V}$, $I_{DS} = 50\% I_{DSS}$	66	75	85	dBm
G_{1dB}	Power Gain at 1dB Gain Compression at $f = 18\text{ GHz}$ $V_{DS} = 5.0\text{V}$, $I_{DS} = 50\% I_{DSS}$	19.0	20.0		
NF_{MIN}	Minimum Noise Figure at $f = 2\text{ GHz}$ $V_{DS} = 3.3\text{V}$, $I_{DS} = 25\% I_{DSS}$	6.5	7.0		dB
η_{ADD}	Power-Added Efficiency		0.8	1.2	dB
I_{MAX}	Maximum Drain-Source Current $V_{DS} = 2\text{V}$ $V_{GS} = +1\text{V}$		45		%
G_M	Transconductance $V_{DS} = 2\text{V}$ $V_{GS} = 0\text{V}$		125		mA
V_P	Pinch-Off Voltage $V_{DS} = 2\text{V}$ $I_{DS} = 1\text{mA}$	60	80		mS
I_{GSO}	Gate-Source Leakage Current $V_{GS} = -5\text{V}$	-0.25	-0.8	-1.5	V
BV_{GS}	Gate-Source Breakdown Voltage $I_{GS} = 1\text{mA}$		1	15	μA
BV_{GD}	Gate-Drain Breakdown Voltage $I_{GD} = 1\text{mA}$	-6	-7		V
		-8	-9		V

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ABSOLUTE MAXIMUM RATINGS (25°C)		
SYMBOL	PARAMETER	RATING ¹
V _{DS}	Drain-Source Voltage	6V
V _{GS}	Gate-Source Voltage	-3V
I _{DS}	Drain-Source Current	2 x I _{DSS}
I _G	Gate Current	5 mA
P _{IN}	RF Input Power	60 mW
T _{CH}	Channel Temperature	175°C
T _{STG}	Storage Temperature	-65/175°C
P _T	Power Dissipation	400mW ^{3,4}

RECOMMENDED CONTINUOUS OPERATING LIMITS		
SYMBOL	PARAMETER	RATING ²
V _{DS}	Drain-Source Voltage	5V
V _{GS}	Gate-Source Voltage	-0.8V
I _{DS}	Drain-Source Current	0.75 x I _{DSS}
I _G	Gate Current	2 mA
P _{IN}	RF Input Power	30 mW
T _{CH}	Channel Temperature	150°C
T _{STG}	Storage Temperature	-20/50°C
P _T	Power Dissipation	350 mW ^{3,4}
G _{XdB}	Gain Compression	6 dB

NOTES:

- Operating conditions that exceed the Absolute Maximum Ratings could result in permanent damage to the device.
- Recommended Continuous Operating Limits should be observed for reliable device operation.
- Power Dissipation defined as: $P_T \equiv (P_{DC} + P_{IN}) - P_{OUT}$, where: P_{DC} = DC bias power, P_{OUT} = RF output power, and P_{IN} = RF input power.
- Power Dissipation to be de-rated as follows above 25°C:
 Absolute Maximum: $P_T = 400\text{mW} - (2.7\text{mW}/^\circ\text{C}) \times T_{HS}$
 Recommended Continuous Operating: $P_T = 350\text{mW} - (2.8\text{mW}/^\circ\text{C}) \times T_{HS}$
 where T_{HS} = heatsink or ambient temperature.
- Specifications subject to change without notice.

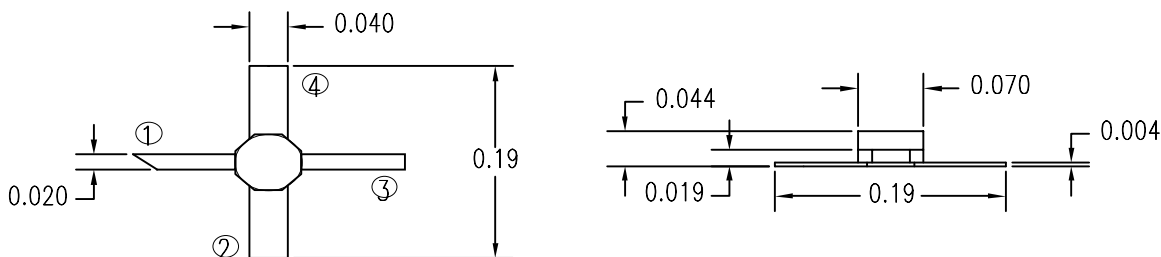
HANDLING PRECAUTIONS:

Proper Electrostatic Discharge (ESD) precautions should be observed at all stages of storage, handling, assembly, and testing. These devices should be treated as Class 1A (0-500V), and further information on ESD control measures can be found in MIL-STD-1686 and MIL-HDBK-263.

PACKAGE CHARACTERISTICS:

The P70-52 package is available with a standard gold over nickel finish. The package lids are epoxy sealed and are capable of passing MIL-STD hermeticity (Gross Leak).

PACKAGE OUTLINE: (DIMENSIONS IN INCHES)



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